

Product Change Notification / KSRA-13AKNI696

Date:

26-Feb-2021

Product Category:

8-bit Microcontrollers, Capacitive Touch Sensors, Touch Controllers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4440 Final Notice: Qualification of MMT as an additional assembly site for selected MTCH112, MTCH810 and PIC12xxxx device families available in 8L DFN (3x3x0.9mm) package.

Affected CPNs:

KSRA-13AKNI696_Affected_CPN_02262021.pdf KSRA-13AKNI696_Affected_CPN_02262021.csv

Notification Text:

PCN Status: Final notification

PCN Type:Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of MMT as an additional assembly site for selected MTCH112, MTCH810 and PIC12xxxx device families available in 8L DFN (3x3x0.9mm) package.

Pre Change:

Assembled at NSEB using gold (Au) or palladium coated copper wire with gold flash (CuPdAu) bond wire, 8600 die attach material, EFTEC-64T lead frame or C194 lead frame material, Ag DAP surface prep or Bare Cu DAP surface prep and without lead lock lead frame

Post Change:

Assembled at NSEB using gold (Au) or palladium coated copper wire with gold flash (CuPdAu) bond wire, 8600 die attach

material, EFTEC-64T lead frame or C194 lead frame material, Ag DAP surface prep or Bare Cu DAP surface prep and without lead lock lead frame

or

Assembled at MMT using palladium coated copper wire with gold flash (CuPdAu) bond wire, 3280 die attach material, C194 lead frame material and Bare Cu DAP surface prep and with lead lock lead frame.

Pre and Post Change Summary:

	Pre C	hange	Post Change						
Assembly Site	UTAC Thai Limi	ited LTD. (NSEB)	UTAC Thai Lir (NSEE		Microchip Technology Thailand (Branch) / MMT				
Wire material	Au	CuPdAu	Au	CuPdAu	CuPdAu				
Die attach material	86	00	8600)	3280				
Molding compound material	G70	OLTD	G700L	TD	G700LTD				
Lead frame material	EFTEC-64T	C194	EFTEC-64T	C194	C194				
Lead Frame DAP Surface Prep	Ag	Bare Cu	Ag	Bare Cu	Bare Cu				
Lead frame lead-lock	N	0	No		Yes				
	See Pre and Post Change attachment for lead frame comparison								

Impacts to Data Sheet:None.

Change Impact:None.

Reason for Change: To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date:

February 10, 2021 (date code: 2107)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2020				→	January 2021				February 2021					
Workweek	45	46	47	48	49	7	01	02	03	04	05	06	07	08	09
Initial PCN Issue Date			Х												
Final PCN Issue Date											Х				
Qual Report Availability															Х
Estimated First Ship Date													Х		

Method to Identify Change:Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:November 20, 2020: Issued initial notification.**January 29, 2021:** Issued final notification. Provided estimated first ship date to be February 10, 2021.**February 26, 2021:** Reissued final notification. Included qual report attachment and updated qual report availability.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_KSRA-13AKNI696_Pre_and_Post Change Summary.pdf PCN_KSRA-13AKNI696 Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile, including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. KSRA-13AKNI696 - CCB 4440 Final Notice: Qualification of MMT as an additional assembly site for selected MTCH112, MTCH810 and PIC12xxxx device families available in 8L DFN (3x3x0.9mm) package.

Affected Catalog Part Numbers (CPN)

PIC12F1822-E/MF PIC12F1822-I/MF043 PIC12F1822-I/MF PIC12F1822T-I/MF PIC12F1822T-E/MF PIC12LF1822-E/MF PIC12LF1822-I/MF PIC12LF1822T-I/MF PIC12F1840-E/MF MTCH810-I/MF PIC12F1840-I/MF PIC12F1840-H/MF MTCH810T-I/MF PIC12F1840T-I/MF PIC12F1840T-E/MF PIC12LF1840-E/MF MTCH112-I/MF PIC12LF1840-I/MF MTCH112T-I/MF PIC12LF1840T-I/MF PIC12F1501-E/MF PIC12F1501-I/MF PIC12F1501T-E/MF PIC12LF1501-E/MF PIC12LF1501-I/MF PIC12F1612-I/MF PIC12LF1612-E/MF PIC12F1571-E/MF PIC12F1572-E/MF PIC12F1571-I/MF059 PIC12F1571-I/MF PIC12F1572-I/MF PIC12F1571T-I/MF059 PIC12F1571T-I/MF PIC12F1572T-I/MF PIC12F1571T-E/MF PIC12F1572T-E/MF PIC12LF1571-E/MF PIC12LF1572-E/MF PIC12LF1571-I/MF PIC12LF1572-I/MF PIC12LF1572T-I/MF PIC12LF1572T-I/MFSIS